

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application for Reissue of
U.S. Patent No. 6,054,198

Filed: Herewith

For: Conformal Thermal Interface Material
For Electronic Components

November 16, 2000

Cleveland, Ohio 44124-4141

BOX REISSUE
COMMISSIONER FOR PATENTS
WASHINGTON, DC 20231

**PRELIMINARY AMENDMENT IN
REISSUE UNDER 37 C.F.R. § 1.173**

Please amend the above-identified application for reissue patent as follows:

IN THE CLAIMS

1. (Amended) A method of conductively cooling a heat-generating electronic component having an operating temperature range above normal room temperature and a first heat transfer surface disposable in thermal adjacency with a second heat transfer surface of a thermal dissipation member to define an interface therebetween, said method comprising the steps of:

(a) providing a thermally-conductive material which is form-stable at normal room temperature in a first phase and conformable in a second phase to substantially fill said interface, said material having a transition temperature from said first phase to said second phase within the operating temperature range of said electronic component, and said material consisting essentially of at least one resin or wax component or mixture thereof blended with at least one thermally-conductive filler;

(b) forming said material into a self-supporting and free-standing film layer, said layer consisting essentially of said material and having a thickness of from about 1-10 mils;

(c) applying said layer to one of said heat transfer surfaces;

(d) disposing said heat transfer surfaces in thermal adjacency to define said interface; and

(e) energizing said electronic component effective to heat said layer to a temperature which is above said phase transition temperature.

9. (Amended) A thermally-conductive interface for interposition between a heat-generating electronic component having an operating temperature range above normal room temperature and a first heat transfer surface disposable in thermal adjacency with a